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October 2010

# 74AUP1G98 TinyLogic<sup>®</sup> Low Power Universal Configurable Two-Input Logic Gate

#### **Features**

- 0.8V to 3.6V V<sub>CC</sub> Supply Operation
- 3.6V Over-Voltage Tolerant I/Os at V<sub>CC</sub> from 0.8V to 3.6V
- High Speed tpp
  - 3.0ns: Typical at 3.3V
- Power-Off High-Impedance Inputs and Outputs
- Low Static Power Consumption
  - I<sub>CC</sub>=0.9µA Maximum
- Low Dynamic Power Consumption
  - CPD=2.5pF Typical at 3.3V
- Ultra-Small MicroPak™ Packages

### Description

The 74AUP1G98 is a universal configurable 2-input logic gate that provides a high performance and low power solution ideal for battery-powered portable applications. This product is designed for a wide low voltage operating range (0.8V to 3.6V) and guarantees very low static and dynamic power consumption across the entire voltage range. All inputs are implemented with hysteresis to allow for slower transition input signals and better switching noise immunity.

The 74AUP1G98 provides for multiple functions as determined by various configurations of the three inputs. The potential logic functions provided are MUX, AND, OR, NAND, and NOR, inverter and buffer. Refer to Figures 5 to 11.

# **Ordering Information**

Part Number	Top Mark	Package	Packing Method
74AUP1G98L6X	AE	6-Lead Micropak™, 1.0mm Wide	5000 Units on Tape & Reel
74AUP1G98FHX	AE	6-Lead, MicroPak2™, 1x1mm Body, .35mm Pitch	5000 Units on Tape & Reel

# **Logic Diagram**

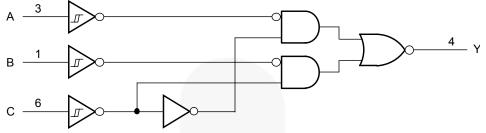


Figure 1. Logic Diagram (Positive Logic)

# **Pin Configurations**

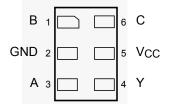


Figure 2. MicroPak™ (Top Through View)

# **Pin Definitions**

Pin # MicroPak™	Name	Description
1	В	Data Input
2	GND	Ground
3	A	Data Input
4	Y	Output
5	V <sub>CC</sub>	Supply Voltage
6	С	Data Input

#### **Function Table**

Inputs			74AUP1G98
С	В	Α	Y=Output
L	L	L	Н
L	L	Н	Н
L	Н	L	L
L	Н	Н	L
Н	L	L	Н
Н	L	Н	L
Н	Н	L	Н
Н	Н	Н	L

H = HIGH Logic Level L = LOW Logic Level

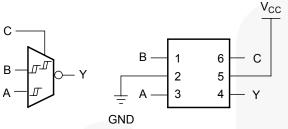
# **Function Selection Table**

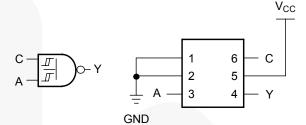
2-Input Logic Function	Connection Configuration
2-to-1 MUX with Inverted Output	Figure 3
2-Input NAND Gate	Figure 4
2-Input NOR Gate with One Inverted Input	Figure 5
2-Input AND Gate with One Inverted Input	Figure 5
2-Input NAND Gate with One Inverted Input	Figure 6
2-Input OR Gate with One Inverted Input	Figure 6
2-Input NOR Gate	Figure 7
Buffer	Figure 8
Inverter	Figure 9

# 74AUP1G98 Logic Configurations

Figure 3 through Figure 9 show the logical functions that can be implemented using the 74AUP1G98. The diagrams show the DeMorgan's equivalent logic duals for a given two-input function. The logical

implementation is next to the board-level physical implementation of how the pins of the function should be connected.





#### Note:

- When C is L, Y=B.
- 2. When C is H,  $Y=\overline{A}$ .

Figure 3. 2-to-1 MUX with Inverted Output

Figure 4. 2-Input NAND Gate

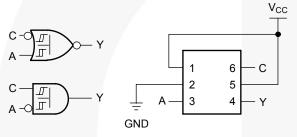


Figure 5. Input NOR Gate with One Inverted Input Figure 6. 2-Input AND Gate with One Inverted Input

Figure 6. 2-Input NAND Gate with One Inverted Input 2-Input OR Gate with One Inverted Input

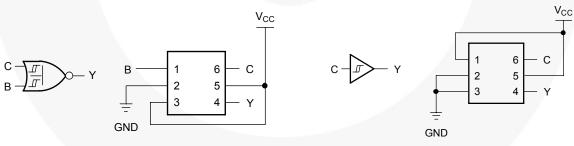


Figure 7. 2-Input NOR Gate

Figure 8. Buffer

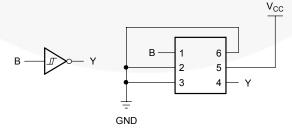


Figure 9. Inverter

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Para	ımeter	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage		-0.5	4.6	V
V <sub>IN</sub>	DC Input Voltage		-0.5	4.6	V
	DC Output Voltage	HIGH or LOW State <sup>(3)</sup>	-0.5	V <sub>CC</sub> + 0.5	V
V <sub>OUT</sub>	DC Output Voltage	V <sub>CC</sub> =0V	-0.5	4.6	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < 0V		-50	mA
	DC Outrout Diada Current	V <sub>OUT</sub> < 0V		-50	A
I <sub>OK</sub>	DC Output Diode Current	V <sub>OUT</sub> > V <sub>CC</sub>		+50	mA
I <sub>OH</sub> / I <sub>OL</sub>	DC Output Source / Sink Curre		±50	mA	
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground Current per	Supply Pin		±50	mA
T <sub>STG</sub>	Storage Temperature Range		-65	+150	°C
TJ	Junction Temperature Under Bi	ias		+150	°C
TL	Junction Lead Temperature, Sc	oldering 10s		+260	°C
A	Dower Dissipation at 195°C	MicroPak-6		130	mW
	Power Dissipation at +85°C	MicroPak2-6		120	
ESD	Human Body Model, JEDEC:JE		5000+	V	
ESD	Charged Device Model, JEDEC	:JESD22-C101		2000	V

#### Note:

# Recommended Operating Conditions<sup>(4)</sup>

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage		0.8	3.6	V
V <sub>IN</sub>	Input Voltage		0	3.6	V
V	Output Voltage	V <sub>CC</sub> =0V	0	3.6	V
$V_{OUT}$	Output Voltage	HIGH or LOW State	0	V <sub>CC</sub>	]
		V <sub>CC</sub> =3.0V to 3.6V		±4.0	
	Output Current	V <sub>CC</sub> =2.3V to 2.7V		±3.1	mA
1 /1		V <sub>CC</sub> =1.65V to 1.95V		±1.9	
I <sub>OH</sub> /I <sub>OL</sub>		V <sub>CC</sub> =1.4V to 1.6V		±1.7	
		V <sub>CC</sub> =1.1V to 1.3V		±1.1	
		V <sub>CC</sub> =0.8V		±20.0	μA
T <sub>A</sub>	Operating Temperature, Free Air		-40	+85	°C
	The more I Decistors of	MicroPak-6		500	
	Thermal Resistance	MicroPak2-6		560	

#### Note:

4. Unused inputs must be held HIGH or LOW. They may not float.

<sup>3.</sup> Io absolute maximum rating must be observed.

# **DC Electrical Characteristics**

Cumb at	Donormatan	Voc. Conditions		T <sub>A</sub> =25°C		T <sub>A</sub> =-40 to 85°C		Units	
Symbol	Parameter	V <sub>CC</sub>	Conditions	Min.	Max.	Min.	Max.	Unit	
		0.80		0.30	0.60	0.30	0.60		
		1.10		0.53	0.90	0.53	0.90		
\	Positive Threshold	1.40		0.74	1.11	0.74	1.11	.,	
$V_P$	Voltage	1.65		0.91	1.29	0.91	1.29	V	
		2.30		1.37	1.77	1.37	1.77		
		3.00		1.88	2.29	1.88	2.29		
		0.80		0.10	0.60	0.10	0.60		
		1.10		0.26	0.65	0.26	0.65		
\ <i>/</i>	Negative	1.40		0.39	0.75	0.39	0.75	V	
$V_N$	Threshold Voltage	1.65		0.47	0.84	0.47	0.84	V	
		2.30		0.69	1.04	0.69	1.04		
		3.00		0.88	1.24	0.88	1.24		
		0.80		0.07	0.50	0.07	0.50		
		1.10		0.08	0.46	0.08	0.46		
V	I hyatawa sia Maltawa	1.40		0.18	0.56	0.18	0.56	\ ,,	
$V_H$	Hysteresis Voltage	1.65		0.27	0.66	0.27	0.66	V	
A		2.30		0.53	0.92	0.53	0.92		
		3.00		0.79	1.31	0.79	1.31		
		$0.80 \leq V_{CC} \leq 3.60$	I <sub>OH</sub> =-20μA	V <sub>CC</sub> -0.1		V <sub>CC</sub> -0.1			
		1.10 ≤ V <sub>CC</sub> ≤ 1.30	I <sub>OH</sub> =-1.1mA	0.75 x V <sub>CC</sub>		0.70 x V <sub>CC</sub>			
		$1.40 \le V_{CC} \le 1.60$	I <sub>OH</sub> =-1.7mA	1.11		1.03			
	HIGH Level Output	$1.65 \le V_{QC} \le 1.95$	I <sub>OH</sub> =-1.9mA	1.32		1.30		.,	
$V_{OH}$	Voltage		I <sub>OH</sub> =-2.3mA	2.05		1.97		V	
		$2.30 \leq V_{CC} \leq 2.70$	I <sub>OH</sub> =-3.1mA	1.90		1.85			
			I <sub>OH</sub> =-2.7mA	2.72		2.67			
		$3.00 \le V_{CC} \le 3.60$	I <sub>OH</sub> =-4.0mA	2.60		2.55			
		$0.80 \le V_{CC} \le 3.60$	I <sub>OL</sub> =20μA		0.10		0.10		
		1.10 ≤ V <sub>CC</sub> ≤ 1.30	I <sub>OL</sub> =1.1mA		0.30 x V <sub>CC</sub>		0.30 x V <sub>CC</sub>		
		1.40 ≤ V <sub>CC</sub> ≤ 1.60	I <sub>OL</sub> =1.7mA		0.31		0.37		
	LOW Level Output	$1.65 \le V_{GC} \le 1.95$	I <sub>OL</sub> =1.9mA		0.31		0.35		
$V_{OL}$	Voltage		I <sub>OL</sub> =2.3mA		0.31		0.33	V	
	V	$2.30 \leq V_{CC} \leq 2.70$	I <sub>OL</sub> =3.1mA		0.44		0.45		
			I <sub>OL</sub> =2.7mA		0.31		0.33		
		$2.70 \le V_{CC} \le 3.60$	I <sub>OL</sub> =4.0mA		0.44		0.45		
I <sub>IN</sub>	Input Leakage Current	0V to 3.6V	$0 \le V_{IN} \le 3.6$		±0.1		±0.5	μA	
I <sub>OFF</sub>	Power Off Leakage Current	0V	$0 \leq (V_{IN}, V_O) \leq 3.6$		0.2		0.6	μ	
$\Delta l_{OFF}$	Additional Power Off Leakage Current	0V to 0.2V	V <sub>IN</sub> or V <sub>O</sub> =0V to 3.6V		0.2		0.6	μA	
	Quiescent Supply	0.0)/ += 2.0)/	V <sub>IN</sub> - V <sub>CC</sub> or GND		0.5		0.9		
Icc	Current	0.8V to 3.6V	$V_{\text{CC}} \leq V_{\text{IN}} \leq 3.6$				±0.9	μA	
$\Delta I_{CC}$	Increase in I <sub>CC</sub> per Input	3.3V	V <sub>IN</sub> =V <sub>CC</sub> -0.6V		40.0		50.0	μA	

# **AC Electrical Characteristics**

					T <sub>A</sub> =25°0	<b>C</b>	T <sub>A</sub> =-40	to 85°C		
Symbol	Parameter	V <sub>CC</sub>	Conditions	Min.	Тур.	Max.	Min.	Max.	Units	Figure
		0.80			25.3					
		$1.10 \le V_{CC} \le 1.30$		2.9	8.7	12.9	2.7	13.2		
		$1.40 \le V_{CC} \le 1.60$	C =5°E D =4MO	2.4	5.1	7.7	2.4	8.3		
		$1.65 \le V_{CC} \le 1.95$	$C_L=5pF, R_L=1M\Omega$	2.2	4.4	6.3	1.9	7.0		
		$2.30 \leq V_{CC} \leq 2.70$		2.0	3.5	4.8	1.8	5.4		
		$3.00 \leq V_{CC} \leq 3.60$		1.5	3.1	4.2	1.5	4.5		
		0.80			26.7					
		$1.10 \le V_{CC} \le 1.30$		3.3	8.5	14.5	3.0	15.1		
		1.40 ≤ V <sub>CC</sub> ≤ 1.60	C <sub>L</sub> =10pF,	2.7	5.8	8.8	2.8	9.5		
		1.65 ≤ V <sub>CC</sub> ≤ 1.95	$R_L=1M\Omega$	2.5	4.7	7.2	2.3	8.0		
		$2.30 \le V_{CC} \le 2.70$		1.9	3.6	5.3	1.9	5.9		
	Propagation	$3.00 \leq V_{CC} \leq 3.60$		1.5	3.1	4.7	1.5	4.9	no	Figure 10
t <sub>PHL</sub> , t <sub>PLH</sub>	Delay	0.80	C <sub>L</sub> =15pF, R <sub>L</sub> =1MΩ		29.8				ns	Figure 11
		$1.10 \le V_{CC} \le 1.30$		3.6	9.9	16.1	3.3	16.9	-	
		1.40 ≤ V <sub>CC</sub> ≤ 1.60		3.0	6.2	9.7	3.1	10.5		
	, 3	1.65 ≤ V <sub>CC</sub> ≤ 1.95		2.8	5.3	7.9	2.5	8.9		
		$2.30 \leq V_{CC} \leq 2.70$		2.5	4.1	5.9	2.5	6.6		
		$3.00 \leq V_{CC} \leq 3.60$		1.7	3.3	5.2	1.7	5.5		
		0.80			27.5					
		$1.10 \le V_{CC} \le 1.30$		3.4	9.1	18.5	3.4	19.0		
		$1.40 \le V_{CC} \le 1.60$	C <sub>L</sub> =30pF,	3.1	5.7	10.5	3,1	11.0		
		1.65 ≤ V <sub>CC</sub> ≤ 1.95	$R_L=1M\Omega$	2.7	4.7	8.7	2.7	9.5		
		$2.30 \leq V_{CC} \leq 2.70$		1.7	3.5	6.5	1.7	7.1		
		$3.00 \leq V_{CC} \leq 3.60$		1.3	3.0	5.6	1.3	6.3		
C <sub>IN</sub>	Input Capacitance	0			2.1				pF	
C <sub>OUT</sub>	Output Capacitance	0			3.0				pF	
		0.80			1.7					
		$1.10 \le V_{CC} \le 1.30$			1.8				pF	V -
_	Power Dissipation	$1.40 \le V_{CC} \le 1.60$	V <sub>IN</sub> =0V or V <sub>CC</sub> ,		1.81					
C <sub>PD</sub>	Capacitance	$1.65 \leq V_{CC} \leq 1.95$	f=10MHz		1.84					
		$2.30 \leq V_{CC} \leq 2.70$			2.1					
		$3.00 \leq V_{CC} \leq 3.60$			2.5				- 2	

# **AC Loadings and Waveforms**

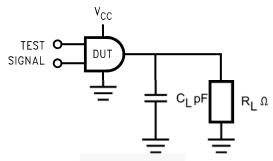


Figure 10. AC Test Circuit

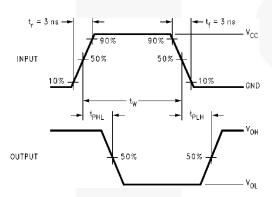
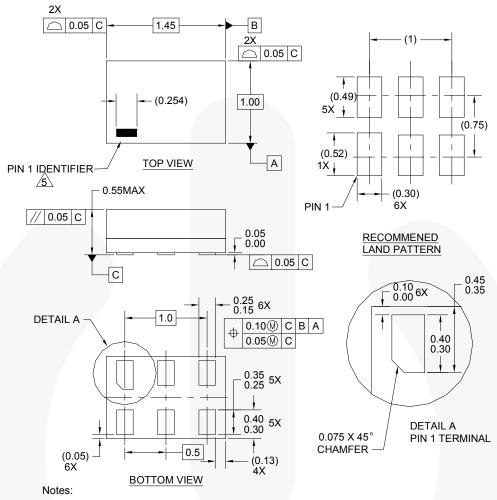


Figure 11. AC Waveforms

		V <sub>cc</sub>				
Symbol	3.3V ± 0.3V	2.5V ± 0.2V	1.8V ± 0.15V	1.5V ± 0.10V	1.2V ± 0.10V	0.8V
$V_{mi}$	V <sub>CC</sub> /2					
$V_{mo}$	V <sub>CC</sub> /2					

# **Physical Dimensions**



- 1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-1994
- 4. FILENAME AND REVISION: MAC06AREV4
- 5. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY

OTHER LINE IN THE MARK CODE LAYOUT.

Figure 12. 6-Lead, MicroPak™, 1.0mm Wide

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/packaging/.

#### **Tape and Reel Specifications**

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/products/logic/pdf/micropak\_tr.pdf.

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
L6X	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

# **Physical Dimensions**

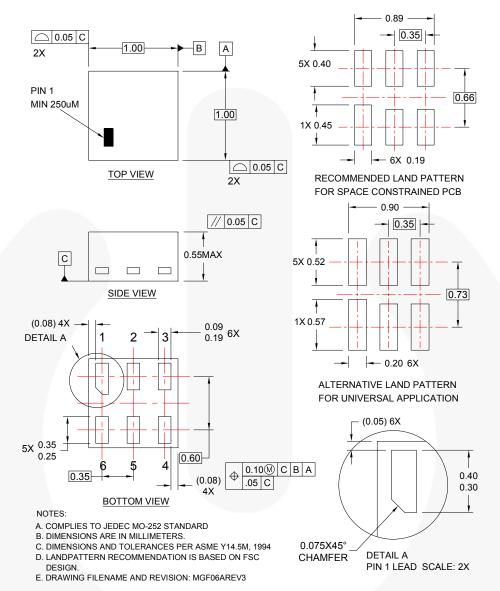


Figure 13. 6-Lead, MicroPak2, 1x1mm Body, .35mm Pitch

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#### **Tape and Reel Specifications**

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/packaging/MicroPAK2 6L tr.pdf.

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
FHX	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed





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FPS™

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Global Power Resource<sup>s™</sup> Green FPS™

Green FPS™ e-Series™ G*m*ax™ GTO™

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MicroFETTM

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MicroPak2™
MillerDrive™
MotionMax™
Motion-SPM™
OptoHiT™
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OPTOPLANAR®

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QFET® QS™ Quiet Series™ RapidConfigure™

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